



*From Nano to Micro Power Electronics
And Packaging Workshop
October the 11th and 12th, 2017
Tours, France*



PRELIMINARY PROGRAMME

Technical Committee: Stéphane BELLENGER, éolane, France – General Chairman
Daniel ALQUIER, Greman Laboratory, France - Chairman
Christophe SERRE, ST Microelectronics, France - Chairman
Nicolas VIVET, ST Microelectronics, France – SAM3 Programme coordinator
Lars BOETTCHER, Fraunhofer Institute IZM, Germany
Cyril BUTTAY, Ampère Laboratory, France
Jean-Luc DIOT, Minapack, France
Guo-Quan LU, Virginia Tech, USA
Jürgen SCHUDERER, ABB Corporate Research, Switzerland
Sébastien JACQUES, Greman Laboratory, France

FIRST DAY CONFERENCE PROGRAMME (October the 11th, 2017)

8h30 **Workshop package and badge distribution**

9h30 **Welcome: workshop programme presentation**

10h00 **SAM3 conference introduction:**

“Growing importance of assembly and packaging” K. Pressel, Infineon.

11h00 **Coffee break / Table Top Exhibition**

11h30 **Failure Analysis Session**

11h30 “CIVA, a promising simulation software for acoustic microscopy applications”, P. Serre, Predictive Image.

12h00 **Table Top Exhibition visit**

12h30 **Lunch (Buffet)**

13h30 **Failure Analysis Session**

13h30 “Defect localization in 3D System-in-Packages based on Lock-in-Thermography and GHz-Scanning Acoustic Microscopy”, F. Altmann, FWMH-CAM.

14h00 “Complex Package Failure Analysis Flow Enablers and Accelerators”, A. Reverdy, Sector Technology.

14h30 “Combined preparation flow of high precision laser tool with Plasma-FIB for SiP failure”, F. Felux, Infineon.

15h00 **Coffee break / Table Top Exhibition**

15h15 **Failure Analysis Session**

15h15 “Latest development for failure analysis – When ions meet chemistry”, G. Goupil, Tescan, Orsay-Physics

16h00 **End of session**

SECOND DAY CONFERENCE PROGRAMME (October the 12th, 2017)

9h00 *Workshop package and badge distribution*

9h30 **Welcome: Second day workshop programme presentation**

9h45 **Keynotes:**

“Additive Manufacturing of Power Electronics Magnetics”, Guo-Quan Lu, VirginiaTech USA

10h30 **Coffee break / Table Top Exhibition**

11h00 **Session Materials, Processes & Technologies**

11h00 “Investigation on Cu-Sn inter-diffusion for power semi-conductor packaging”, Yousra Bettahi, ST Microelectronics Tours, France

11h25 “Hybrid silver sintering die-attach paste for multi-die packaging of mid-power solutions”, Alexandre Val, ASE Europe, Bruxelles, Belgium

11h50 “Reliability analysis of Cu-Sn intermetallic joints elaborated at low temperature by transient Liquid Phase Bonding Process”, Jean-Luc Diot, Composite Innovation, Pessac, France

12h15 **Table Top Exhibition visit**

13h00 **Lunch (Buffet)**

14h00 **Keynotes:**

“Panel Level Packaging for Power Applications”, Rolf Aschenbrenner, IZM Fraunhofer Institute, Berlin, Germany

14h45 **Coffee break / Table Top Exhibition**

15h15 **Session Materials, Processes & Technologies**

15h15 “Fine Pitch Solder Bumping by Printing through Dry Film Photo Resist”, Gabriel Parès, CEA-Leti, Grenoble, France

15h40 “Bipolar Step-up Converter with MPPT for Thermal Energy Harvesting Systems”, Loreto Mateu, Fraunhofer Institute, Nuremburg, Germany

16h05 “Shielding’s effect of radiating components”, Zana Kari, Greman institute, Tours, France

16h30 **End of session**

Next to the first workshop sessions of 11th of October, an exceptional event will be organized for which you need to register if you wish to attend:

- *On Wednesday, October the 11th from 16:30 a visit of the famous Amboise castle near Tours town is organized. Departure from Greman’s institute at 16h30*
- *After the Castle visit, a dinner in a gastronomic restaurant in Montlouis-sur-Loire is organized as well*

Sponsors:



éolane

International Microelectronics and Packaging Society – France
17 rue de l’Amiral Hamelin 75016 Paris. Phone: +33 (0)1 45 05 72 32
E-mail : imaps.france@imapsfrance.org

Registration Form
Final registration October the 2nd, 2017

COMPANY:

NAME:

FIRSTNAME:

ADDRESS:

TEL:

E-MAIL:

→ Send back to Florence Vireton Fax : +33 (0)1 45 05 72 32

E-mail: imaps.france@imapsfrance.org

FEES (include lunch, breaks & 2-days events)

Conferences on free access on website www.imapsfrance.org after the event.

IMAPS MEMBER 220 € HT excluding - 263.12 € TTC

Non IMAPS MEMBER 250 € HT - 299.00 € TTC

SPEAKERS/CHAIRS 180 € HT - 215.28 € TTC

Table Top 300 € HT - 358, 80 € TTC (1 table, chairs, panel, conferences attendance, coffee breaks, lunch). **For foreign companies, VAT is excluded**

Do not forget to tick boxes if you want to participate

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| - Visit of a typical Touraine castle (Wednesday evening) | yes | no |
| - Dinner after the visit (Wednesday evening) | yes | no |

On line Payment and Registration available on www.france.imapseurope.org

PAYMENT BANK REFERENCES

Credit card accepted, as well as payment by cheque, cash or wire transfer. BNP PARIBAS
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Quartier des Deux Lions

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